Series 655000 TSOP-to-DIP 0.600 [15.24] Adapter

FEATURES

- Designed to allow user to cut 32-position adapter down to any size desired.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.

GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4 with 1-oz. Cu traces
- PADS: bare Cu protected with Entek® by Enthone or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

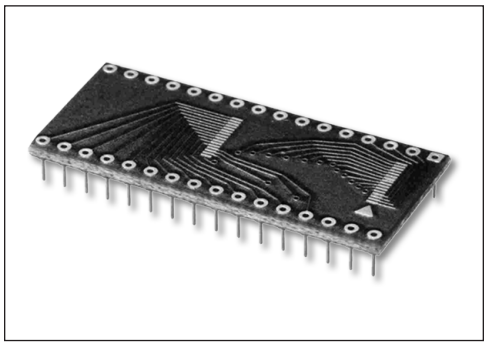
MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- Will plug into standard IC sockets

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

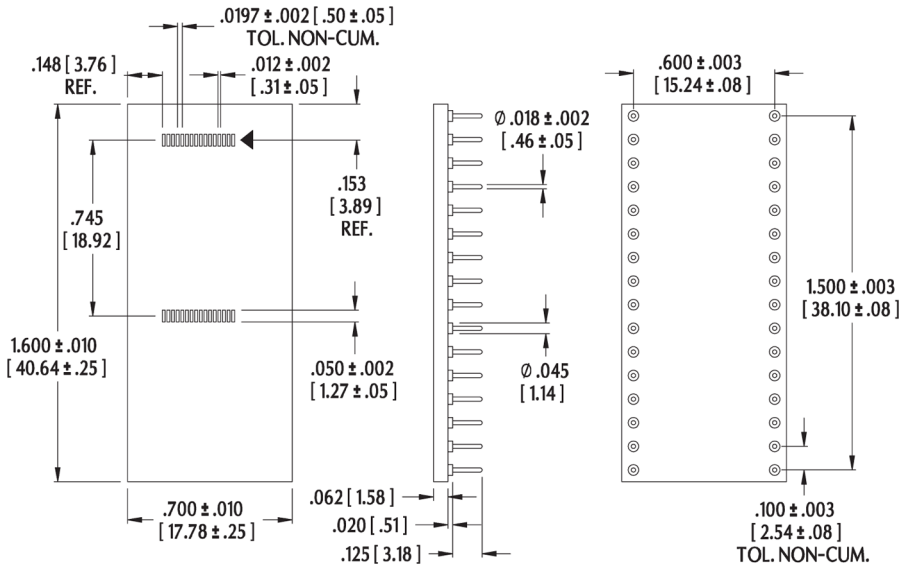


CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE**: Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

32-655000-10

32-655000-10-P for Panelized Version



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